Soldering Temperature	T_{sol}	260	

NOTE1: 100εs pulse, 100Hz frequency
NOTE2: AC for 1minute, R.H.=40~60%

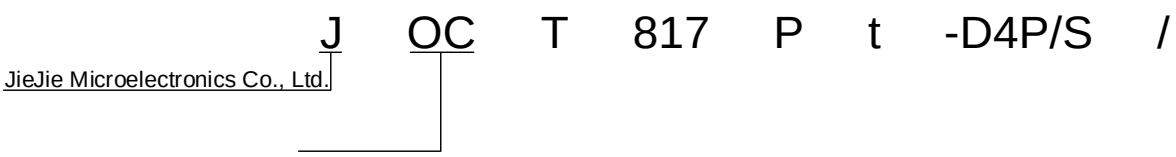
ELECTRICAL CHARACTERISTICS (Temperature=25ÁC)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	εA
	Terminal Capacitance	C_t	V=0,f=1MHz	-	30	250	pF
Output	Collector-Emitter dark current	I_{CEO}	V_{CE}=20V, I_F=0	-	-	100	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	I_C=0.1mA I_F=0	80	-	-	V
	Emitter-Collector breakdown voltage	BV_{ECO}	I_E=0.1mA I_F=0	7	-	-	V
Transfer Characteristics	Current transfer ratio	CTR	I_F=5mA V_{CE}=5V	100	-	400	%
	Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	I_F=20mA I_C=2mA	-	0.06	0.4	V
	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	-	-	q
	Floating Capacitance	C_{IO}	V=0, f=1MHz	-	10	-	pF
	Cut-off Frequency	f_c	V_{CE}=5V, I_C=2mA R_L=100q, -3dB	-	80	-	kHz
	Rise Time	t_r	V_{CC}=5V, I_C=2mA R_L=100q	-	3	18	εs
	Fall Time	t_f		-	4	18	εs
	Turn On Time	t_{on}	V_{CC}=5V, I_F=16mA R_L=1.9kq	-	5	-	εs
	Turn Off Time	t_{off}		-	60	-	εs

NOTE1: Rank Table of Current Transfer Ratio (Temperature=25°C)

CTR Rank **Min. (%)** ‡M ‰

ORDERING INFORMATION



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

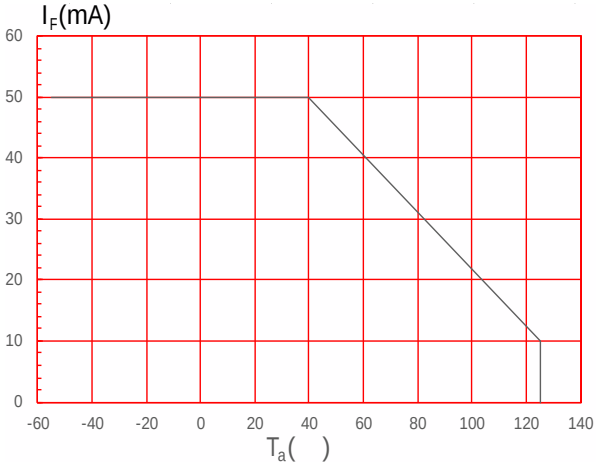


FIG.2: Collector Power Dissiption vs. Ambient Temperature

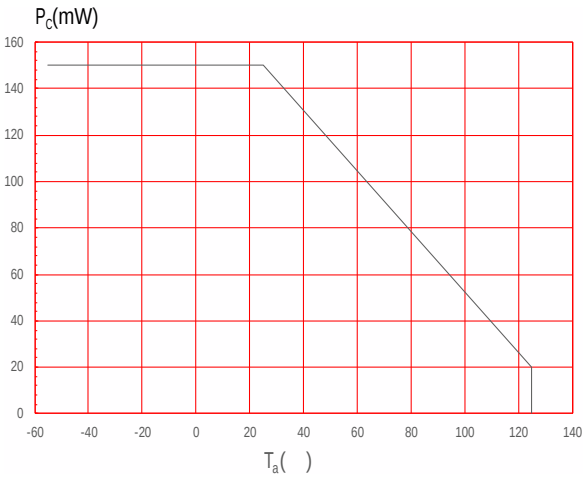


FIG.3: Forward Current vs. Forward Voltage

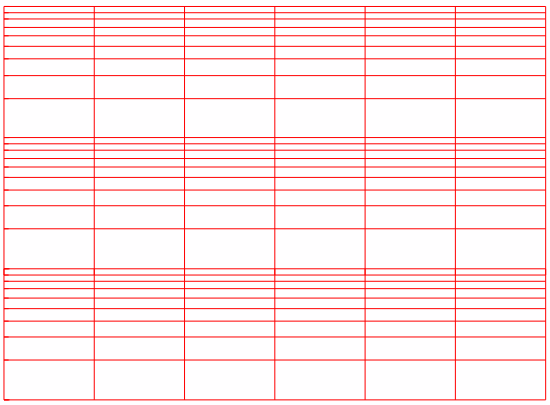


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

Test Circuits

FIG.11: Test Circuits of Response Time

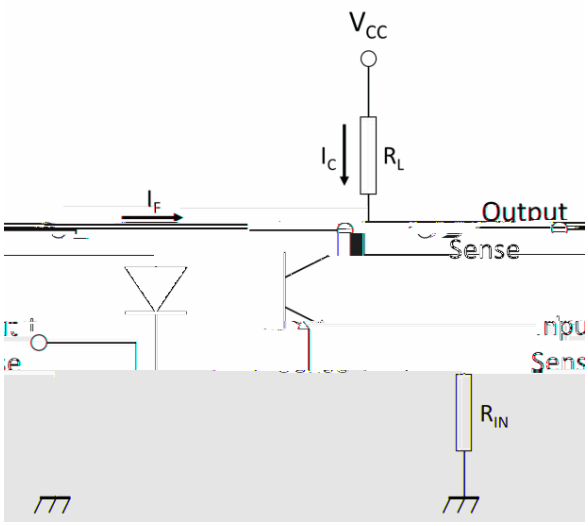
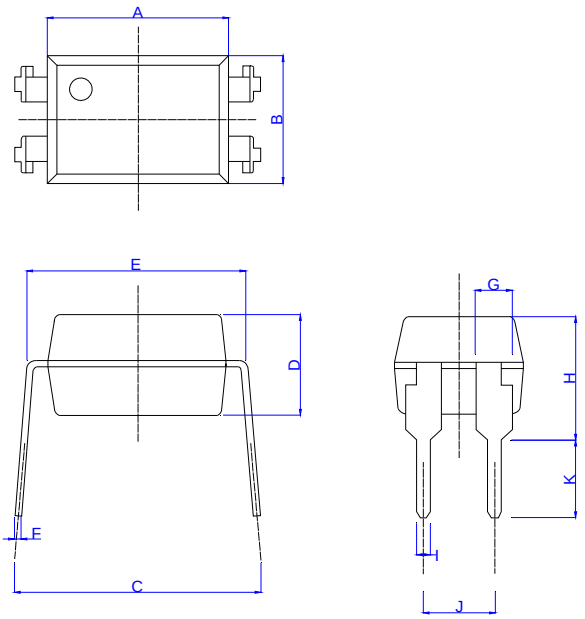


FIG.12: Curves of Response Time

FIG.13: Test Circuits of Frequency Response

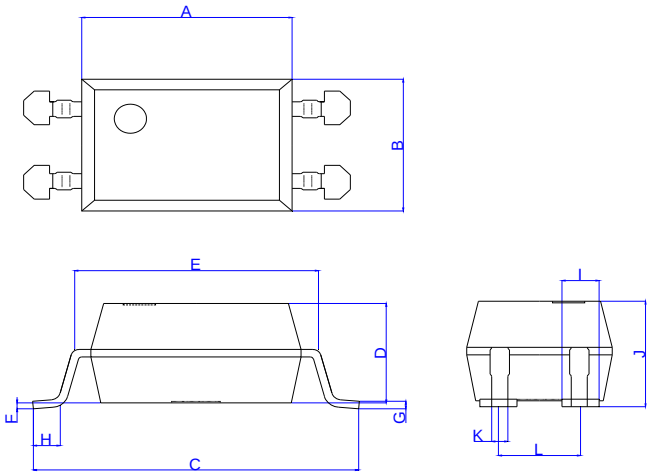
Package Dimension (Unit: mm)

Standard DIP Type:



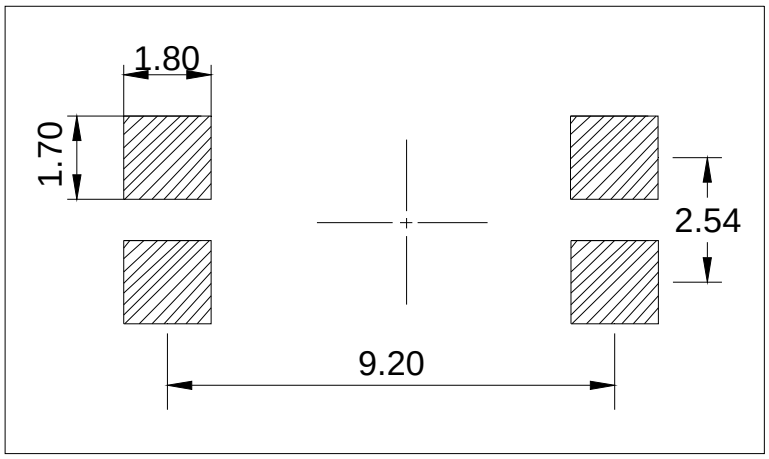
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30	6.50	6.70	0.248	0.256	0.264
B	4.30	4.50	4.70	0.169	0.177	0.185
C	7.62	8.56	9.50	0.300	0.337	0.374
D	3.20	3.40	3.60	0.126	0.134	0.142
E	7.32	7.62	7.92	0.288	0.300	0.312
F	0.15	0.25	0.35	0.006	0.100	0.014
G	0.95	1.15	1.35	0.037	0.045	0.053
H	4.20	4.50	4.80	0.165	0.177	0.189
I	0.40	0.50	0.60	0.016	0.020	0.024
J	2.29	2.54	2.79	0.090	0.100	0.110
K	2.50	2.80	3.10	0.098	0.110	0.122

Option SMD Type:



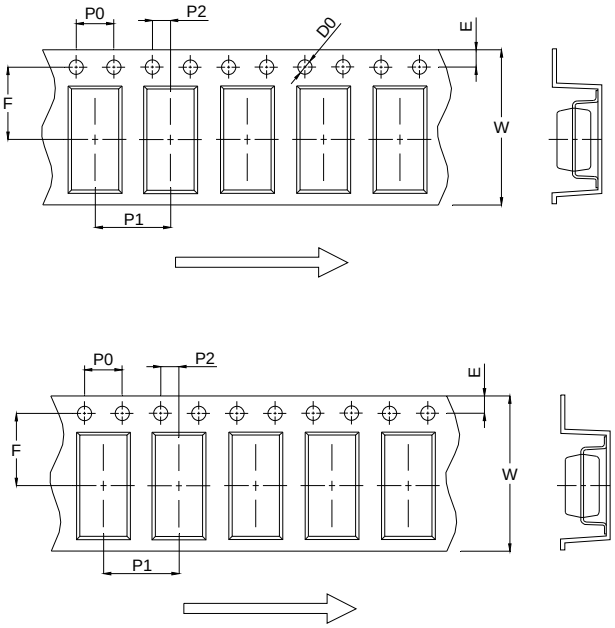
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30	6.50	6.70	0.248	0.256	0.264
B	4.30	4.50	4.70	0.169	0.177	0.185
C	9.80	10.10	10.40	0.386	0.398	0.409
D	3.20	3.40	3.60	0.126	0.134	0.142
E	7.32	7.62	7.92	0.288	0.300	0.312
F	0.00	0.20	0.40	0.000	0.008	0.016
G	0.06	0.26	0.46	0.002	0.010	0.018
H	0.70	1.00	1.30	0.028	0.039	0.051
I	0.95	1.15	1.35	0.037	0.045	0.053
J	3.40	3.60	3.80	0.134	0.142	0.150
K	0.30	0.50	0.70	0.012	0.020	0.028
L	2.29	2.54	2.79	0.090	0.100	0.110

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



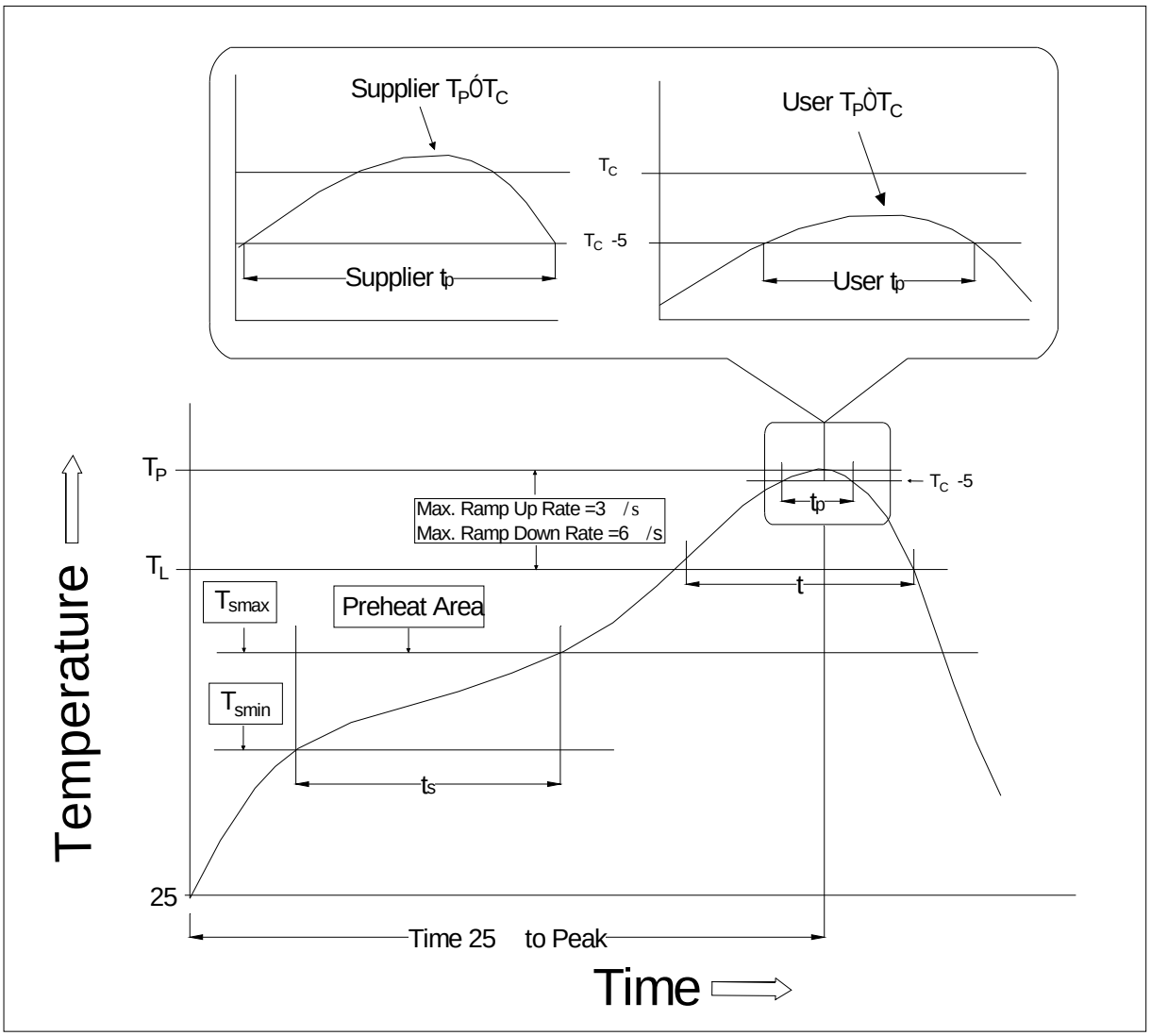
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

T1



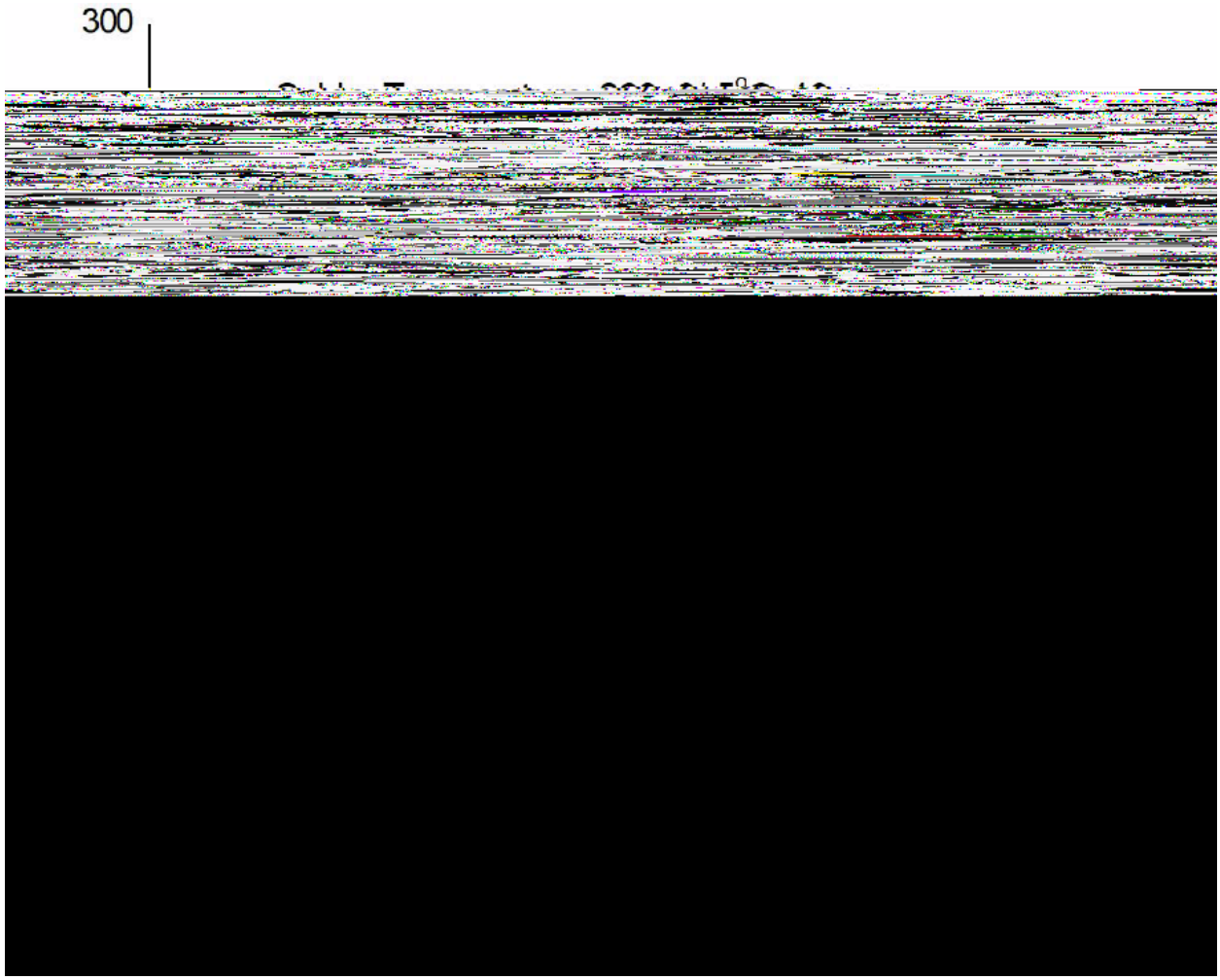
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50			0.059	
P0		4.00			0.157	
P1		8.00			0.315	
P2		2.00			0.079	
E		1.75			0.069	
F		7.50			0.295	
		0.40			0.016	
W		16.00			0.630	

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40ÁC;

Recommend storage humidity: <60%;

MSL level: MSL 1

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